

## Encapsulation Technologies For Electronic Applications Materials And Processes For Electronic Applications

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Encapsulation Technologies for Electronic Applications Offers a comprehensive discussion of encapsulants in electronic applications. This work emphasizes on the Encapsulation of microelectronic devices.

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In electronics, potting is a process of filling a complete electronic assembly with a solid or gelatinous compound for high voltage assemblies by excluding gaseous phenomena such as corona discharge, for resistance to shock and vibration, and for the exclusion of water, moisture, or corrosive agents. Thermosetting plastics or silicone rubber gels are often used, though epoxy resins are also ...

Encapsulation Technologies for Electronic Applications

A number of accelerated tests (damp heat tests) are used to qualify the effectiveness of the encapsulation technology, to slow down the extrinsic degradation of the device. Usually, damp heat tests can last 500/1000 hours and the deterioration of a set of selected operational parameters is monitored.

Encapsulation Technologies Incorporated - Innovative ...

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Encapsulation Technologies for Electronic Applications. ... The application of thermoset encapsulation of electronic parts offers a wide range of advantages with respect to thermal, mechanical and ...

Encapsulation Technologies For Electronic Applications

Encapsulation techniques used in electronic applications can be classified into five main technologies: molding, glob-topping, potting, underfilling, and printing.

Encapsulation Technologies for Electronic Applications ...

Encapsulation Technologies for Electronic Applications, Second Edition, offers an updated, comprehensive discussion of encapsulants in electronic applications, with a primary emphasis on the encapsulation of microelectronic devices and connectors and transformers. It includes sections on 2-D and 3-D packaging and encapsulation, encapsulation materials, including environmentally friendly 'green' encapsulants.

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Many electronic applications that traditionally used hermetic packages such as military are now using commercial-off-the-shelf (COTS) plastic packages. Plastic encapsulation has the advantages of low cost, smaller form factors, and improved manufacturability.

????-Encapsulation Technologies for Electronic ...

Encapsulation Technologies for Electronic Applications is primarily focused on the encapsulation of microelectronic devices, with additional attention paid to the encapsulation of connectors and transformers. Various encapsulation techniques are explained including molding, potting, glob-topping, underfilling and printing encapsulation.

Encapsulation technologies for electronic applications ...

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